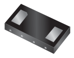
Package Details

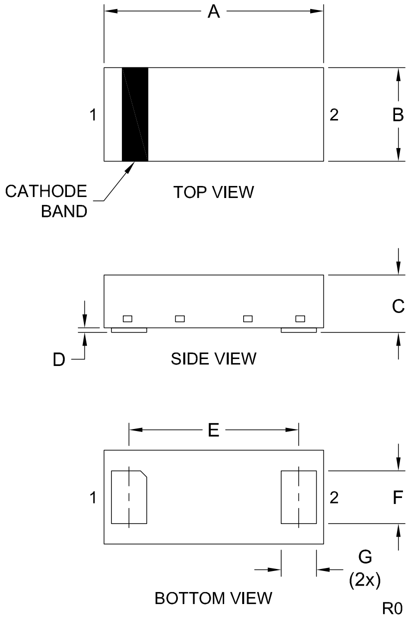
DFN123F Case


Top View


Bottom View

Central Semiconductor Corp.

Mechanical Drawing

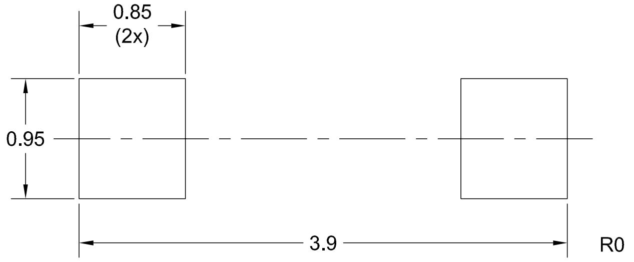


DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.144	0.152	3.65	3.85
B	0.059	0.067	1.50	1.70
C	0.031	0.039	0.80	1.00
D	0.000	0.002	0.00	0.05
E	0.110	0.118	2.80	3.00
F	0.033	0.037	0.85	0.95
G	0.020	0.028	0.50	0.70

DFN123F (REV: R0)

Part Marking: 4-6 Character Alpha/Numeric Code

Mounting Pad Geometry (Dimensions in mm)



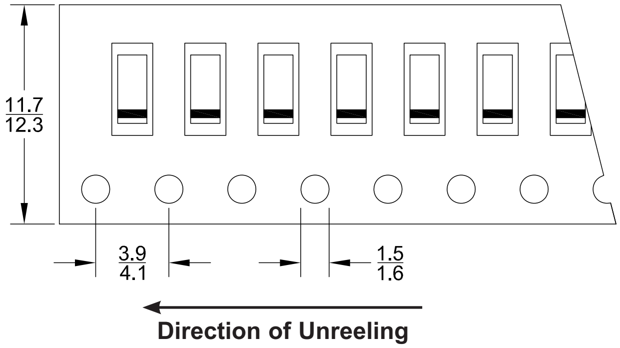
R1 (18-December 2020)

Package Details

DFN123F Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 12mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-D

Packaging Base

7” Reel = 3,000 pcs.
13” Reel = 10,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code and Ship Date.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	7	4
	18	54,000	9x9x9	23x23x23	14	7
	40	120,000	21x9x9	53x23x23	30	14
	108	324,000	27x9x17	69x23x43	78	36s
13”	5	50,000	15x4x15	38x10x38	7	4
	14	140,000	15x15x9	38x38x23	19	9
	26	260,000	15x15x18	38x38x46	34	16

Ordering Information

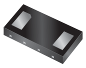
- For devices taped and reeled on 7” reels, add TR suffix to part number.
- For devices taped and reeled on 13” reels, add TR13 suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

R1 (18-December 2020)

Material Composition Specification

DFN123F Case


Top View


Bottom View

Device average mass . . . . **14.25 mg**
Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.105%	0.300	Si	7440-21-3	2.11%	0.300	21,053
bond wire	gold	0.154%	0.022	Au	7440-57-5	0.15%	0.022	1,544
leadframe	copper alloy	25.916%	3.693	Cu	7440-50-8	25.71%	3.664	257,123
				Si	7440-21-3	0.18%	0.025	1,754
				Mg	7439-95-4	0.03%	0.004	281
	plating	0.765%	0.109	Ni	7440-02-0	0.73%	0.104	7,298
				Pd	7440-05-3	0.03%	0.004	281
				Au	7440-57-5	0.01%	0.001	70
die attach	silver epoxy	0.519%	0.074	Ag	7440-22-4	0.36%	0.051	3,579
				epoxy resin	Proprietary	0.16%	0.023	1,614
encapsulation	EMC GREEN	70.540%	10.052	silica (fused)	60676-86-0	68.94%	9.824	689,404
				epoxy resin	29690-82-2	0.71%	0.101	7,088
				phenol resin	9003-35-4	0.71%	0.101	7,088
				carbon black	1333-86-4	0.18%	0.025	1,754
				metal hydroxide	1309-42-8	0.01%	0.001	70

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (29-October 2019)